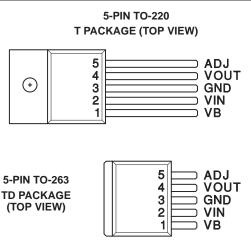
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- **Fast Transient Response**
- 10-mA to 3-A Load Current
- **Short Circuit Protection**
- Maximum Dropout of 450-mV at 3-A Load Current
- Separate Bias and VIN Pins
- Available in Adjustable or Fixed-Output Voltages
- 5-Pin Package Allows Kelvin Sensing of • Load Voltage
- **Reverse Current Protection**



Note: Tab = Ground

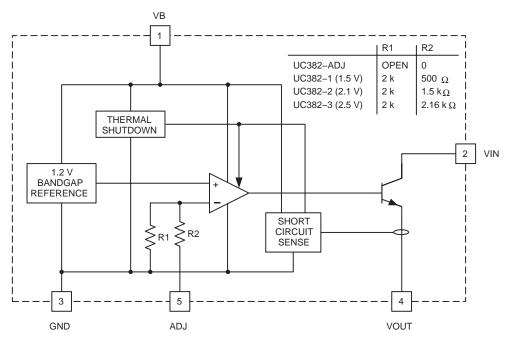
description

The UC382 is a low-dropout-linear regulator providing a quick response to fast load changes. Combined with its precision onboard reference, the UC382 excels at driving GTL and BTL buses. Due to its fast response to load transients, the total capacitance required to decouple the regulator's output can be significantly decreased when compared to standard LDO linear regulators.

Dropout voltage (VIN to VOUT) is only 450 mV maximum at 100°C and 350 mV typical at 3-A load.

The onboard bandgap reference is stable with temperature and scaled for a 1.2-V input to the internal-power amplifier. The UC382 is available in fixed-output voltages of 1.5 V, 2.1 V, or 2.5 V. The output voltage of the adjustable version can be set with two external resistors. If the external resistors are omitted, the output voltage defaults to 1.2 V.

block diagram



UDG-00080



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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absolute maximum ratings over operating free-air temperature (unless otherwise noted)^{†‡}

| VB | 13 V |
|--|------------------|
| VIN | 7.5 V |
| Output voltage | . 1.2 V to 6.0 V |
| Storage temperature, T _{stg} | –65°C to 150°C |
| Junction temperature, T _J | –55°C to 150°C |
| Lead temperature (soldering, 10 seconds) | 300°C |

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

‡Currents are positive into, negative out of the specified terminal. Consult Packaging Section of Databook for thermal limitations and considerations of packages.

AVAILABLE OPTIONS⁽¹⁾

| | | | | PACKAGE | D DEVICES | | | | |
|----------------|--------|--------|---------|--------------|----------------------------|---------|---------|--------------|--|
| _ | | TO-2 | 20 (T) | | TO-263 (TD) ⁽²⁾ | | | | |
| Тј | | OUTPUT | VOLTAGE | | OUTPUT VOLTAGE | | | | |
| | 1.5 V | 2.1 V | 2.5 V | 1.2 V or ADJ | 1.5 V | 2.1 V | 2.5 V | 1.2 V or ADJ | |
| –40°C to 100°C | 282T-1 | 282T-2 | 282T-3 | 282T-ADJ | 282TD-1 | 282TD-2 | 282TD-3 | 282TD-ADJ | |
| 0°C to 100°C | 382T-1 | 382T-2 | 382T-3 | 382T-ADJ | 382TD-1 | 382TD-2 | 382TD-3 | 382TD-ADJ | |

1. For more package and ordering information, see the Package Option Addendum located at the end of this data sheet.

2. For 50 piece reel, add KTTT (e.g., UC282TDKTTT-1); for 500 piece reel, add TR (e.g., UC282TDTR-1).

electrical characteristics, $T_A = -40^{\circ}$ C to 100° C for the UC282-X series and 0° C to 100° C for the UC382-X, VB = 5 V, VIN = 3.3 V, VOUT = 2.5 V for the UC382-ADJ, $T_A = T_J$, (unless otherwise stated)

UC382-3 fixed 2.5 V, 3-A family

| PARAMETERS | TE | ST CONDITIONS | MIN | TYP | MAX | UNITS |
|---|----------------------------------|---------------|-------|-------|-------|-------|
| | UC382-3 | | 2.475 | 2.500 | 2.525 | V |
| Output voltage (I _{VOUT} = 100 mA) | UC282-3 | | 2.450 | 2.500 | 2.525 | V |
| Load regulation | I _{VOUT} = 10 mA to 3 A | ł | | 0.5 | 4 | mV |
| VIN PSSR | | | 80 | 100 | | dB |
| VB PSSR | | | 50 | 60 | | dB |
| | I _{VOUT} = 3 A, | TJ = 25°C | | 350 | 425 | mV |
| VIN dropout voltage = VIN–VOUT | I _{VOUT} = 3 A, | UC382-3 | | 350 | 450 | mV |
| | I _{VOUT} = 3 A, | UC282-3 | | 350 | 500 | mV |
| | I _{VOUT} = 3 A, | UC382-3 | | 1.8 | 2.10 | V |
| VB dropout = VB–VOUT | I _{VOUT} = 3 A, | UC282-3 | | 1.8 | 2.20 | V |
| Short circuit current limit | | | 3.3 | | 4.5 | А |
| | $I_{VOUT} = 10 \text{ mA}$ | | | 6 | 11 | mA |
| VB current | IVOUT = 3 A | | | 18 | 60 | mA |
| VIN current | IVOUT = 3 A | | 2.94 | 2.97 | | А |



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electrical characteristics, $T_A = -40^{\circ}$ C to 100° C for the UC282-X series and 0° C to 100° C for the UC382-X, VB = 5 V, VIN = 3.3 V, VOUT = 2.5 V for the UC382-ADJ, $T_A = T_J$, (unless otherwise stated)

UC382-2 fixed 2.1 V, 3-A family

| PARAMETERS | TE | ST CONDITIONS | MIN | TYP | MAX | UNITS |
|---|--|-----------------------|-------|-------|-------|-------|
| | UC382-2 | | 2.079 | 2.100 | 2.121 | V |
| Output voltage (I _{VOUT} = 100 mA) | UC282-2 | | 2.058 | 2.100 | 2.121 | V |
| Load regulation | $I_{VOUT} = 10 \text{ mA to } 3 \text{ A}$ | Ą | | 0.5 | 4 | mV |
| VIN PSSR | | | 80 | 100 | | dB |
| VB PSSR | | | 52 | 62 | | dB |
| | I _{VOUT} = 3 A, | T _J = 25°C | | 350 | 425 | mV |
| VIN dropout voltage = VIN-VOUT | I _{VOUT} = 3 A, | UC382-2 | | 350 | 450 | mV |
| | I _{VOUT} = 3 A, | UC282-2 | | 350 | 500 | mV |
| | I _{VOUT} = 3 A, | UC382-2 | | 1.8 | 2.10 | V |
| VB dropout = VB–VOUT | I _{VOUT} = 3 A, | UC282-2 | | 1.8 | 2.20 | V |
| Short circuit current limit | | | 3.3 | | 4.5 | А |
| | I _{VOUT} = 10 mA | | | 6 | 11 | mA |
| VB current | I _{VOUT} = 3 A | | | 18 | 60 | mA |
| VIN current | I _{VOUT} = 3 A | | 2.94 | 2.97 | | А |

UC382-1 fixed 1.5 V, 3-A family

| PARAMETERS | TE | ST CONDITIONS | MIN | TYP | MAX | UNITS |
|---|----------------------------------|-----------------------|-------|-------|-------|-------|
| | UC382-1 | | 1.485 | 1.500 | 1.515 | V |
| Output voltage (I _{VOUT} = 100 mA) | UC282-1 | | 1.470 | 1.500 | 1.515 | V |
| Load regulation | I _{VOUT} = 10 mA to 3 A | ۱. | | 0.5 | 4 | mV |
| VIN PSSR | | | 80 | 100 | | dB |
| VB PSSR | | | 55 | 65 | | dB |
| | I _{VOUT} = 3 A, | T _J = 25°C | | 350 | 425 | mV |
| VIN dropout voltage = VIN–VOUT | I _{VOUT} = 3 A, | UC382-1 | | 350 | 450 | mV |
| | I _{VOUT} = 3 A, | UC282-1 | | 350 | 500 | mV |
| | I _{VOUT} = 3 A, | UC382-1 | | 1.8 | 2.10 | V |
| VB dropout = VB–VOUT | I _{VOUT} = 3 A, | UC282-1 | | 1.8 | 2.20 | V |
| Short circuit current limit | | | 3.3 | | 4.5 | А |
| | I _{VOUT} = 10 mA | | | 6 | 11 | mA |
| VB current | I _{VOUT} = 3 A | | | 18 | 60 | mA |
| VIN current | I _{VOUT} = 3 A | | 2.94 | 2.97 | | А |



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electrical characteristics, $T_A = -40^{\circ}$ C to 100° C for the UC282-X series and 0° C to 100° C for the UC382-X, VB = 5 V, VIN = 3.3 V, VOUT = 2.5 V for the UC382-ADJ, $T_A = T_J$, (unless otherwise stated)

UC382-ADJ adjustable, 3-A family

| PARAMETERS | TE | ST CONDITIONS | MIN | TYP | MAX | UNITS |
|--|--|-----------------------|-------|-------|-------|-------|
| | UC382-ADJ | | 1.188 | 1.200 | 1.212 | V |
| ADJ voltage (I _{VOUT} = 100 mA) | UC282-ADJ | | 1.176 | 1.200 | 1.212 | V |
| Load regulation | $I_{VOUT} = 10 \text{ mA to } 3 \text{ /}$ | IVOUT = 10 mA to 3 A | | | | mV |
| VIN PSSR | VOUT programmed for | or 2.5 V | 80 | 100 | | dB |
| VB PSSR | VOUT programmed for | or 2.5 V | 50 | 60 | | dB |
| | I _{VOUT} = 3 A, | T _J = 25°C | | 350 | 425 | mV |
| VIN dropout voltage = VIN–VOUT | IVOUT = 3 A, | UC382-ADJ | | 350 | 450 | mV |
| | I _{VOUT} = 3 A, | UC282-ADJ | | 350 | 500 | mV |
| | I _{VOUT} = 3 A, | UC382-ADJ | | 1.8 | 2.10 | V |
| VB dropout = VB–VOUT | I _{VOUT} = 3 A, | UC282-ADJ | | 1.8 | 2.20 | V |
| Short circuit current limit | | | 3.3 | | 4.5 | А |
| | IVOUT = 10 mA | | | 6 | 11 | mA |
| VB current | IVOUT = 3 A | | | 18 | 60 | mA |
| VIN current | IVOUT = 3 A | | 2.94 | 2.97 | | А |

pin descriptions

ADJ: In the adjustable version, the user programs the output voltage with two external resistors. The resistors should be 0.1% for high accuracy. The output amplifier is configured as a non-inverting-operational amplifier. The resistors should meet the criteria of R3 || R4 < 100 Ω . Connect ADJ to VOUT for an output voltage of 1.2 V. Note that the point at which the feedback network is connected to the output is the Kelvin sense point. For -1, -2, and -3 versions, ADJ pin is tied to VOUT to obtain specified output voltage.

GND: For accurate results, the GND pin should be referenced to the load ground.

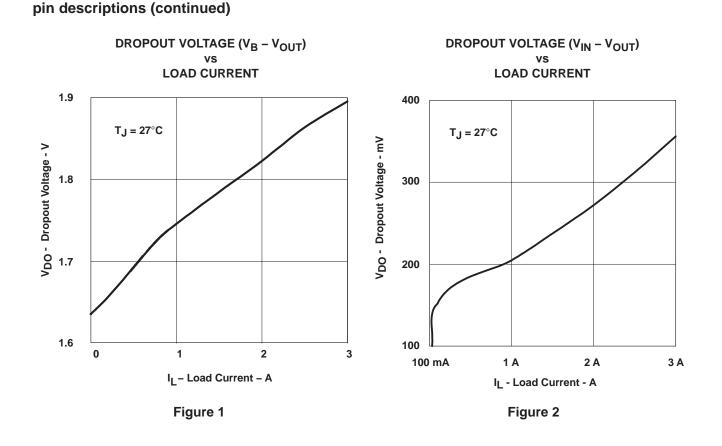
VB: Supplies power to all circuits of the regulator except the collector of the output-power transistor. The 2-V headroom from VB to VOUT allows the use of a Darlington output stage for inherently-low-output impedance and fast response. (Dropout is derated for junction temperatures below 0°C.)

VIN: Supplies the current to the collector of the output-power transistor only. The dropout (VIN–VOUT) is under 100 mV for light loads; maximum dropout is 450 mV at 3 A for $T_J = 0^{\circ}C$ to 100°C. (Dropout is derated for junction temperatures over 100°C.) At full load, the majority of the VB current is going to the load.

VOUT: This pin should be connected to the load via a low impedance path. Avoid connectors which add significant inductance and resistance. Note that even though a Kelvin sense is available through a 5-pin package, care must be taken since voltage drops along wire traces add to the dropout voltage.



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APPLICATION INFORMATION

The UC382 is easy to use. The adjustable version requires two 0.1% resistors to set the output voltage. The fixed versions of the UC382 require no external resistors. All versions of the UC382 require decoupling capacitors on the input and output. In a typical application, VB and VIN are driven from switching power supplies which may have large filter capacitors at their outputs. If the UC382 is further than 12 inches from the power supply, it is recommended to add local decoupling as close as possible to the linear regulator.

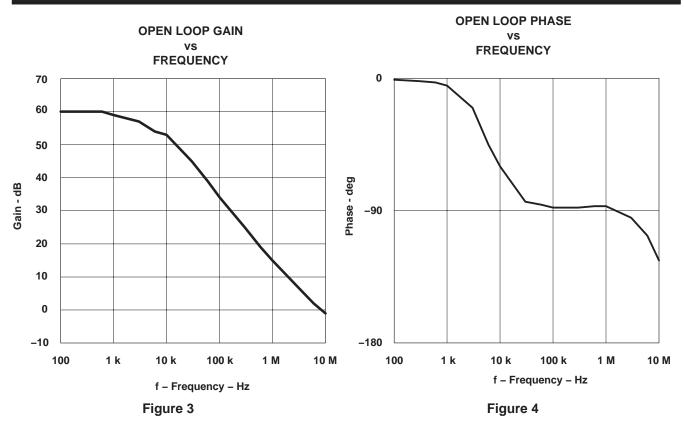
Decouple the output of the UC382 with at least 100 μ F of high-quality tantalum or Sanyo OSCON capacitors close to the VOUT pin for maximum stability. Many applications involving Ultra-Fast GTL or BTL applications require additional capacitance close to the load. The exact amount will vary according to speed and magnitude of the load transients and the tolerance allowed for transients on VOUT. When specifying the decoupling capacitors, the series resistance of the capacitor bank is an important factor in its ability to filter load transients.

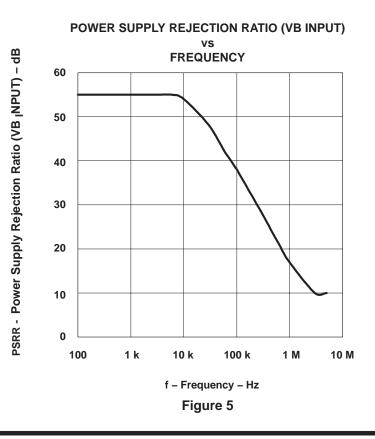
The UC382 allows for Kelvin sensing the voltage at the load. This improves regulation performance and eliminates the voltage drops due to wire-trace resistance. This voltage drop must be added to the headroom (VIN to VOUT and VB to VOUT). The dropout of 450 mV is measured at the pins and does not include additional drops due to trace resistance. The minimum load current is 10 mA.

Two or more UC382's may be used in parallel. While stable, this arrangement does degrade the transient response.



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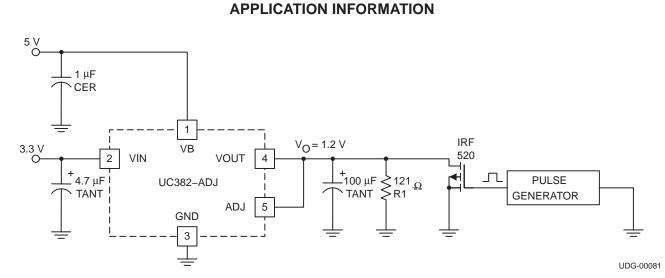
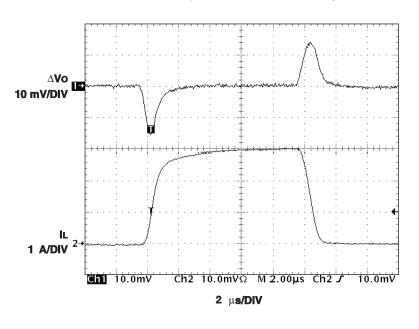


Figure 6. Transient Test Circuit



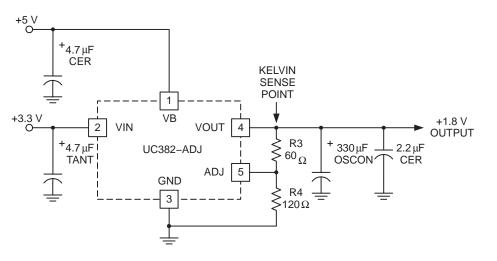
10 mA to 3 A/ μ s Load Transient Response

Figure 7



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APPLICATION INFORMATION





UDG-00082

UDG-00083

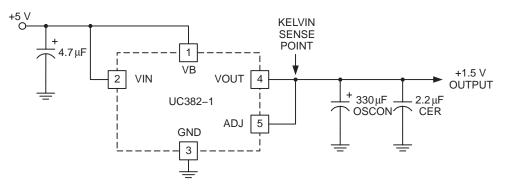


Figure 9. Typical UC382-1, -2, or -3 Application





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PACKAGING INFORMATION

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/ Ball Finish | MSL Peak Temp ⁽³⁾ | Samples (Requires Login) |
|------------------|-----------------------|------------------|--------------------|------|-------------|----------------------------|----------------------|------------------------------|-----------------------------|
| UC282T-1 | ACTIVE | TO-220 | KC | 5 | 50 | Green (RoHS & no Sb/Br) | CU SN | N / A for Pkg Type | |
| UC282T-1G3 | ACTIVE | TO-220 | KC | 5 | 50 | Green (RoHS & no Sb/Br) | CU SN | N / A for Pkg Type | |
| UC282T-2 | ACTIVE | TO-220 | KC | 5 | 50 | Green (RoHS & no Sb/Br) | CU SN | N / A for Pkg Type | |
| UC282T-2G3 | ACTIVE | TO-220 | KC | 5 | 50 | Green (RoHS & no Sb/Br) | CU SN | N / A for Pkg Type | |
| UC282T-3 | ACTIVE | TO-220 | KC | 5 | 50 | Green (RoHS & no Sb/Br) | CU SN | N / A for Pkg Type | |
| UC282T-3G3 | ACTIVE | TO-220 | KC | 5 | 50 | Green (RoHS & no Sb/Br) | CU SN | N / A for Pkg Type | |
| UC282T-ADJ | ACTIVE | TO-220 | KC | 5 | 50 | Green (RoHS & no Sb/Br) | CU SN | N / A for Pkg Type | |
| UC282T-ADJG3 | ACTIVE | TO-220 | KC | 5 | 50 | Green (RoHS & no Sb/Br) | CU SN | N / A for Pkg Type | |
| UC282TD-1 | OBSOLETE | DDPAK/ TO-263 | KTT | 5 | | TBD | Call TI | Call TI | |
| UC282TD-2 | OBSOLETE | DDPAK/ TO-263 | KTT | 5 | | TBD | Call TI | Call TI | |
| UC282TD-3 | OBSOLETE | DDPAK/ TO-263 | KTT | 5 | | TBD | Call TI | Call TI | |
| UC282TD-ADJ | OBSOLETE | DDPAK/ TO-263 | KTT | 5 | | TBD | Call TI | Call TI | |
| UC282TDKTTT-1 | ACTIVE | DDPAK/ TO-263 | KTT | 5 | 50 | Green (RoHS & no Sb/Br) | CU SN | Level-2-260C-1 YEAR | |
| UC282TDKTTT-1G3 | ACTIVE | DDPAK/ TO-263 | KTT | 5 | 50 | Green (RoHS & no Sb/Br) | CU SN | Level-2-260C-1 YEAR | |
| UC282TDKTTT-2 | ACTIVE | DDPAK/ TO-263 | KTT | 5 | 50 | Green (RoHS & no Sb/Br) | CU SN | Level-2-260C-1 YEAR | |
| UC282TDKTTT-2G3 | ACTIVE | DDPAK/ TO-263 | KTT | 5 | 50 | Green (RoHS & no Sb/Br) | CU SN | Level-2-260C-1 YEAR | |
| UC282TDKTTT-3 | ACTIVE | DDPAK/ TO-263 | KTT | 5 | 50 | Green (RoHS & no Sb/Br) | CU SN | Level-2-260C-1 YEAR | |



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| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/ Ball Finish | MSL Peak Temp ⁽³⁾ | Samples (Requires Login) |
|-------------------|-----------------------|------------------|--------------------|------|-------------|----------------------------|----------------------|------------------------------|-----------------------------|
| UC282TDKTTT-3G3 | ACTIVE | DDPAK/ TO-263 | KTT | 5 | 50 | Green (RoHS & no Sb/Br) | CU SN | Level-2-260C-1 YEAR | |
| UC282TDKTTT-ADJ | ACTIVE | DDPAK/ TO-263 | KTT | 5 | 50 | Green (RoHS & no Sb/Br) | CU SN | Level-2-260C-1 YEAR | |
| UC282TDKTTT-ADJG3 | ACTIVE | DDPAK/ TO-263 | KTT | 5 | 50 | Green (RoHS & no Sb/Br) | CU SN | Level-2-260C-1 YEAR | |
| UC282TDTR-1 | ACTIVE | DDPAK/ TO-263 | KTT | 5 | 500 | Green (RoHS & no Sb/Br) | CU SN | Level-2-260C-1 YEAR | |
| UC282TDTR-1G3 | ACTIVE | DDPAK/ TO-263 | KTT | 5 | 500 | Green (RoHS & no Sb/Br) | CU SN | Level-2-260C-1 YEAR | |
| UC282TDTR-3 | ACTIVE | DDPAK/ TO-263 | KTT | 5 | 500 | Green (RoHS & no Sb/Br) | CU SN | Level-2-260C-1 YEAR | |
| UC282TDTR-3G3 | ACTIVE | DDPAK/ TO-263 | KTT | 5 | 500 | Green (RoHS & no Sb/Br) | CU SN | Level-2-260C-1 YEAR | |
| UC282TDTR-ADJ | ACTIVE | DDPAK/ TO-263 | KTT | 5 | 500 | Green (RoHS & no Sb/Br) | CU SN | Level-2-260C-1 YEAR | |
| UC282TDTR-ADJG3 | ACTIVE | DDPAK/ TO-263 | KTT | 5 | 500 | Green (RoHS & no Sb/Br) | CU SN | Level-2-260C-1 YEAR | |
| UC382T-1 | ACTIVE | TO-220 | KC | 5 | 50 | Green (RoHS & no Sb/Br) | CU SN | N / A for Pkg Type | |
| UC382T-1G3 | ACTIVE | TO-220 | KC | 5 | 50 | Green (RoHS & no Sb/Br) | CU SN | N / A for Pkg Type | |
| UC382T-2 | ACTIVE | TO-220 | KC | 5 | 50 | Green (RoHS & no Sb/Br) | CU SN | N / A for Pkg Type | |
| UC382T-2G3 | ACTIVE | TO-220 | KC | 5 | 50 | Green (RoHS & no Sb/Br) | CU SN | N / A for Pkg Type | |
| UC382T-3 | ACTIVE | TO-220 | KC | 5 | 50 | Green (RoHS & no Sb/Br) | CU SN | N / A for Pkg Type | |
| UC382T-3G3 | ACTIVE | TO-220 | KC | 5 | 50 | Green (RoHS & no Sb/Br) | CU SN | N / A for Pkg Type | |
| UC382T-ADJ | ACTIVE | TO-220 | KC | 5 | 50 | Green (RoHS & no Sb/Br) | CU SN | N / A for Pkg Type | |
| UC382T-ADJG3 | ACTIVE | TO-220 | KC | 5 | 50 | Green (RoHS & no Sb/Br) | CU SN | N / A for Pkg Type | |
| UC382TD-1 | OBSOLETE | DDPAK/ TO-263 | KTT | 5 | | TBD | Call TI | Call TI | |



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| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/ Ball Finish | MSL Peak Temp ⁽³⁾ | Samples (Requires Login) |
|-------------------|-----------------------|------------------|--------------------|------|-------------|----------------------------|----------------------|------------------------------|-----------------------------|
| UC382TD-2 | OBSOLETE | DDPAK/ TO-263 | KTT | 5 | | TBD | Call TI | Call TI | |
| UC382TD-3 | OBSOLETE | DDPAK/ TO-263 | KTT | 5 | | TBD | Call TI | Call TI | |
| UC382TD-ADJ | OBSOLETE | DDPAK/ TO-263 | KTT | 5 | | TBD | Call TI | Call TI | |
| UC382TDKTTT-1 | ACTIVE | DDPAK/ TO-263 | KTT | 5 | 50 | Green (RoHS & no Sb/Br) | CU SN | Level-2-260C-1 YEAR | |
| UC382TDKTTT-1G3 | ACTIVE | DDPAK/ TO-263 | KTT | 5 | 50 | Green (RoHS & no Sb/Br) | CU SN | Level-2-260C-1 YEAR | |
| UC382TDKTTT-2 | ACTIVE | DDPAK/ TO-263 | KTT | 5 | 50 | Green (RoHS & no Sb/Br) | CU SN | Level-2-260C-1 YEAR | |
| UC382TDKTTT-2G3 | ACTIVE | DDPAK/ TO-263 | KTT | 5 | 50 | Green (RoHS & no Sb/Br) | CU SN | Level-2-260C-1 YEAR | |
| UC382TDKTTT-3 | ACTIVE | DDPAK/ TO-263 | KTT | 5 | 50 | Green (RoHS & no Sb/Br) | CU SN | Level-2-260C-1 YEAR | |
| UC382TDKTTT-3G3 | ACTIVE | DDPAK/ TO-263 | KTT | 5 | 50 | Green (RoHS & no Sb/Br) | CU SN | Level-2-260C-1 YEAR | |
| UC382TDKTTT-ADJ | ACTIVE | DDPAK/ TO-263 | KTT | 5 | 50 | Green (RoHS & no Sb/Br) | CU SN | Level-2-260C-1 YEAR | |
| UC382TDKTTT-ADJG3 | ACTIVE | DDPAK/ TO-263 | KTT | 5 | 50 | Green (RoHS & no Sb/Br) | CU SN | Level-2-260C-1 YEAR | |
| UC382TDTR-1 | ACTIVE | DDPAK/ TO-263 | KTT | 5 | 500 | Green (RoHS & no Sb/Br) | CU SN | Level-2-260C-1 YEAR | |
| UC382TDTR-1G3 | ACTIVE | DDPAK/ TO-263 | KTT | 5 | 500 | Green (RoHS & no Sb/Br) | CU SN | Level-2-260C-1 YEAR | |
| UC382TDTR-2G3 | ACTIVE | DDPAK/ TO-263 | KTT | 5 | | TBD | Call TI | Call TI | |
| UC382TDTR-3 | ACTIVE | DDPAK/ TO-263 | KTT | 5 | 500 | Green (RoHS & no Sb/Br) | CU SN | Level-2-260C-1 YEAR | |
| UC382TDTR-3G3 | ACTIVE | DDPAK/ TO-263 | KTT | 5 | 500 | Green (RoHS & no Sb/Br) | CU SN | Level-2-260C-1 YEAR | |
| UC382TDTR-ADJ | ACTIVE | DDPAK/ TO-263 | KTT | 5 | 500 | Green (RoHS & no Sb/Br) | CU SN | Level-2-260C-1 YEAR | |
| UC382TDTR-ADJG3 | ACTIVE | DDPAK/ TO-263 | KTT | 5 | 500 | Green (RoHS & no Sb/Br) | CU SN | Level-2-260C-1 YEAR | |



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(1) The marketing status values are defined as follows: ACTIVE: Product device recommended for new designs. LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect. NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design. PREVIEW: Device has been announced but is not in production. Samples may or may not be available. OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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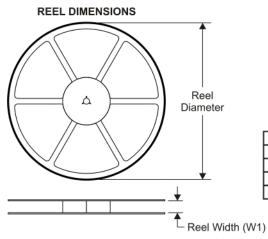
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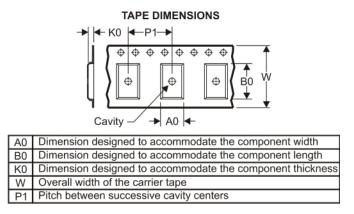
PACKAGE MATERIALS INFORMATION

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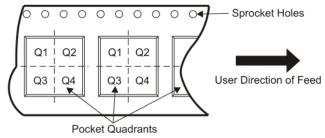
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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|-----------------|------------------|--------------------|------|-----|--------------------------|--------------------------|------------|------------|------------|------------|-----------|------------------|
| UC282TDKTTT-1 | DDPAK/ TO-263 | КТТ | 5 | 50 | 330.0 | 24.4 | 10.6 | 15.6 | 4.9 | 16.0 | 24.0 | Q2 |
| UC282TDKTTT-2 | DDPAK/ TO-263 | КТТ | 5 | 50 | 330.0 | 24.4 | 10.6 | 15.6 | 4.9 | 16.0 | 24.0 | Q2 |
| UC282TDKTTT-3 | DDPAK/ TO-263 | КТТ | 5 | 50 | 330.0 | 24.4 | 10.6 | 15.6 | 4.9 | 16.0 | 24.0 | Q2 |
| UC282TDKTTT-ADJ | DDPAK/ TO-263 | КТТ | 5 | 50 | 330.0 | 24.4 | 10.6 | 15.6 | 4.9 | 16.0 | 24.0 | Q2 |
| UC282TDTR-1 | DDPAK/ TO-263 | КТТ | 5 | 500 | 330.0 | 24.4 | 10.6 | 15.6 | 4.9 | 16.0 | 24.0 | Q2 |
| UC282TDTR-3 | DDPAK/ TO-263 | КТТ | 5 | 500 | 330.0 | 24.4 | 10.6 | 15.6 | 4.9 | 16.0 | 24.0 | Q2 |
| UC282TDTR-ADJ | DDPAK/ TO-263 | КТТ | 5 | 500 | 330.0 | 24.4 | 10.6 | 15.6 | 4.9 | 16.0 | 24.0 | Q2 |
| UC382TDKTTT-1 | DDPAK/ TO-263 | КТТ | 5 | 50 | 330.0 | 24.4 | 10.6 | 15.6 | 4.9 | 16.0 | 24.0 | Q2 |
| UC382TDKTTT-2 | DDPAK/ TO-263 | КТТ | 5 | 50 | 330.0 | 24.4 | 10.6 | 15.6 | 4.9 | 16.0 | 24.0 | Q2 |
| UC382TDKTTT-3 | DDPAK/ TO-263 | КТТ | 5 | 50 | 330.0 | 24.4 | 10.6 | 15.6 | 4.9 | 16.0 | 24.0 | Q2 |
| UC382TDKTTT-ADJ | DDPAK/ | KTT | 5 | 50 | 330.0 | 24.4 | 10.6 | 15.6 | 4.9 | 16.0 | 24.0 | Q2 |

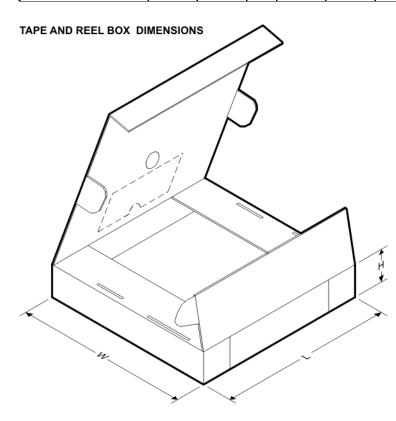
PACKAGE MATERIALS INFORMATION



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| Device | Package Type | Package Drawing | | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|---------------|------------------|--------------------|---|-----|--------------------------|--------------------------|------------|------------|------------|------------|-----------|------------------|
| | TO-263 | | | | | | | | | | | |
| UC382TDTR-1 | DDPAK/ TO-263 | КТТ | 5 | 500 | 330.0 | 24.4 | 10.6 | 15.6 | 4.9 | 16.0 | 24.0 | Q2 |
| UC382TDTR-3 | DDPAK/ TO-263 | КТТ | 5 | 500 | 330.0 | 24.4 | 10.6 | 15.6 | 4.9 | 16.0 | 24.0 | Q2 |
| UC382TDTR-ADJ | DDPAK/ TO-263 | КТТ | 5 | 500 | 330.0 | 24.4 | 10.6 | 15.6 | 4.9 | 16.0 | 24.0 | Q2 |



| *All dimensions are nominal | | | | | | | |
|-----------------------------|--------------|-----------------|------|-----|-------------|------------|-------------|
| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
| UC282TDKTTT-1 | DDPAK/TO-263 | КТТ | 5 | 50 | 346.0 | 346.0 | 41.0 |
| UC282TDKTTT-2 | DDPAK/TO-263 | КТТ | 5 | 50 | 346.0 | 346.0 | 41.0 |
| UC282TDKTTT-3 | DDPAK/TO-263 | КТТ | 5 | 50 | 346.0 | 346.0 | 41.0 |
| UC282TDKTTT-ADJ | DDPAK/TO-263 | КТТ | 5 | 50 | 346.0 | 346.0 | 41.0 |
| UC282TDTR-1 | DDPAK/TO-263 | КТТ | 5 | 500 | 346.0 | 346.0 | 41.0 |
| UC282TDTR-3 | DDPAK/TO-263 | КТТ | 5 | 500 | 346.0 | 346.0 | 41.0 |
| UC282TDTR-ADJ | DDPAK/TO-263 | КТТ | 5 | 500 | 346.0 | 346.0 | 41.0 |
| UC382TDKTTT-1 | DDPAK/TO-263 | КТТ | 5 | 50 | 346.0 | 346.0 | 41.0 |
| UC382TDKTTT-2 | DDPAK/TO-263 | КТТ | 5 | 50 | 346.0 | 346.0 | 41.0 |
| UC382TDKTTT-3 | DDPAK/TO-263 | КТТ | 5 | 50 | 346.0 | 346.0 | 41.0 |
| UC382TDKTTT-ADJ | DDPAK/TO-263 | КТТ | 5 | 50 | 346.0 | 346.0 | 41.0 |



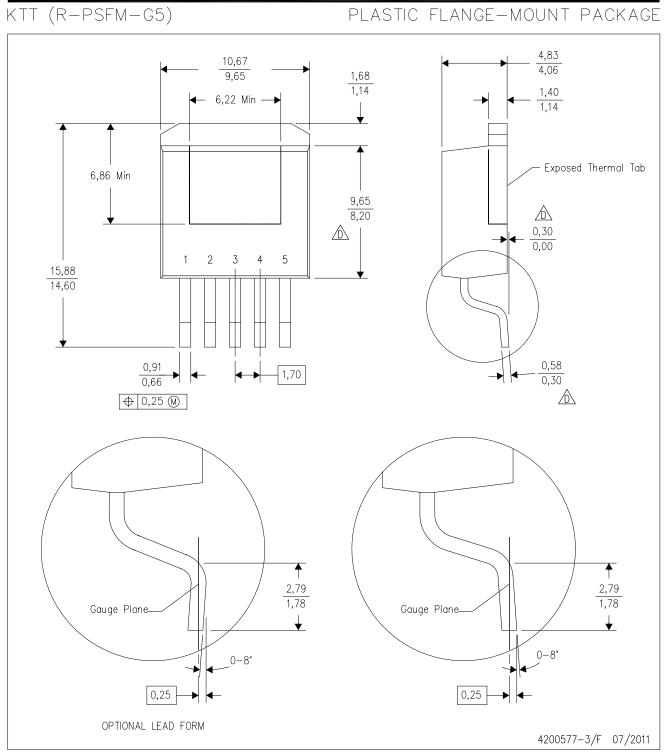


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| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|---------------|--------------|-----------------|------|-----|-------------|------------|-------------|
| UC382TDTR-1 | DDPAK/TO-263 | КТТ | 5 | 500 | 346.0 | 346.0 | 41.0 |
| UC382TDTR-3 | DDPAK/TO-263 | КТТ | 5 | 500 | 346.0 | 346.0 | 41.0 |
| UC382TDTR-ADJ | DDPAK/TO-263 | KTT | 5 | 500 | 346.0 | 346.0 | 41.0 |

MECHANICAL DATA



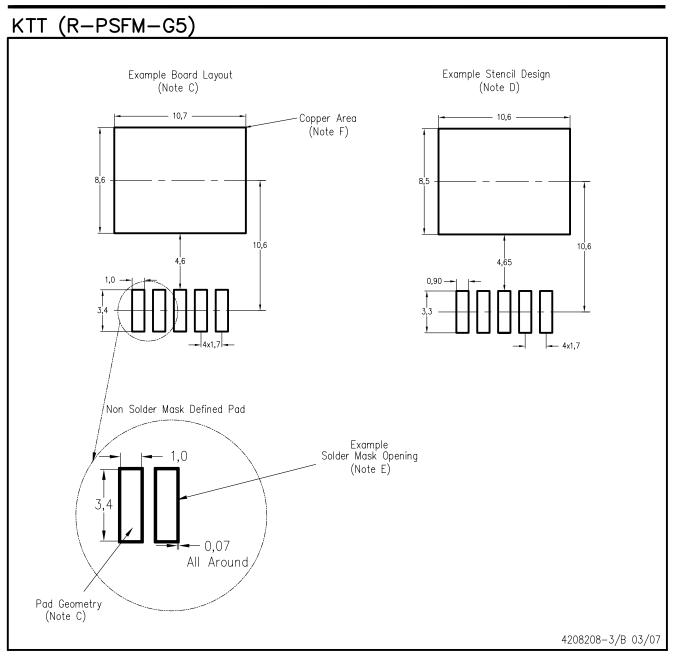
NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion. Mold flash or protrusion not to exceed 0.005 (0,13) per side.

A Falls within JEDEC TO-263 variation BA, except minimum lead thickness, maximum seating height, and minimum body length.





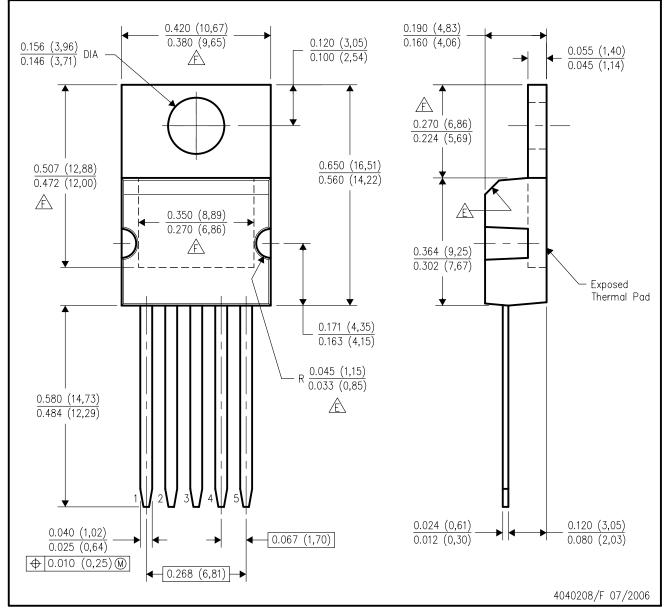
NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-SM-782 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.
- F. This package is designed to be soldered to a thermal pad on the board. Refer to the Product Datasheet for specific thermal information, via requirements, and recommended thermal pad size. For thermal pad sizes larger than shown a solder mask defined pad is recommended in order to maintain the solderable pad geometry while increasing copper area.



KC (R-PSFM-T5)

PLASTIC FLANGE-MOUNT PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. All lead dimensions apply before solder dip.
- D. The center lead is in electrical contact with the mounting tab.
- \not These features are optional.
- A Thermal pad contour optional within these dimensions.



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